

Additive Manufacturing – Module 2

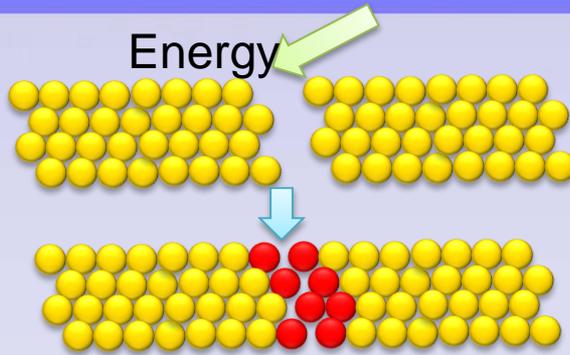
Spring 2015

Wenchao Zhou

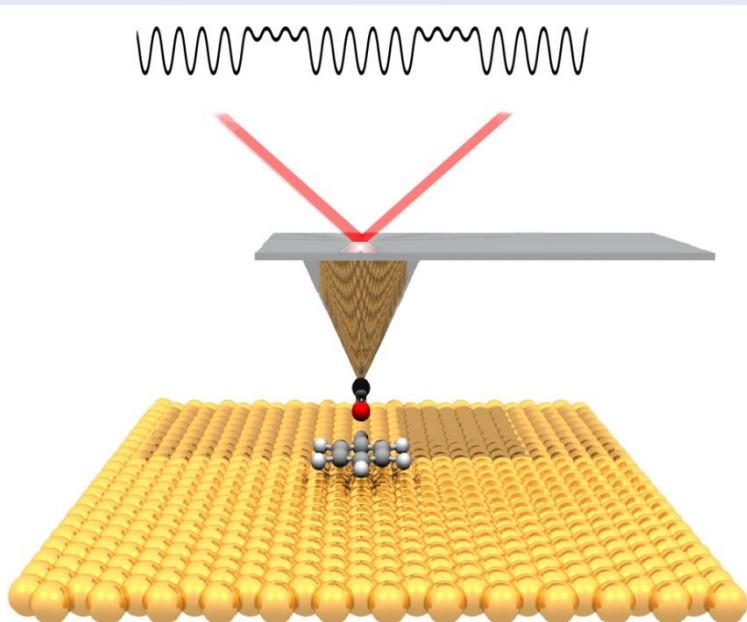
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The Department of Mechanical Engineering
University of Arkansas, Fayetteville



Additive: reducing material interface between material particles



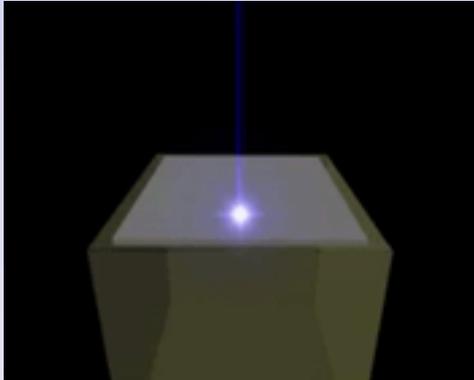
Build atom by atom, bond by bond



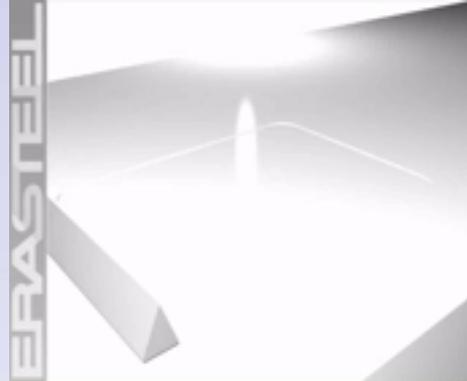
Lego

- ❖ **Material units (atom, droplets, powder particles, etc.)**
- ❖ **Bonding/joining mechanism (need to form new bonds between material units)**
- ❖ **Controlled (forming new bonds in a controlled fashion)**
- ❖ **Source of control (pattern energy or materials or both)**

- What is AM
- Applications
- How does it work
- Advantages
- Opportunities
- Challenges
- AM Industry



Stereolithography



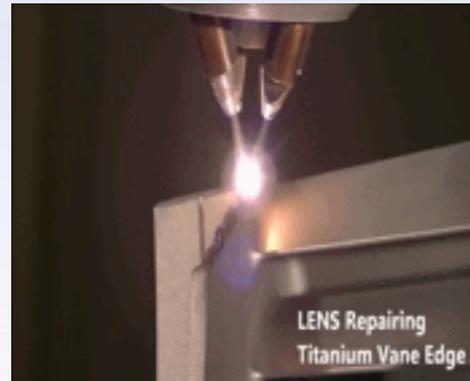
Selective Laser Melting
Powder bed fusion processes



Fused Deposition Modeling
Extrusion based processes



Inkjet deposition
Printing based processes



Laser Engineered Net
Shaping Beam deposition
processes



Laminated Object
Manufacturing Sheet
lamination processes

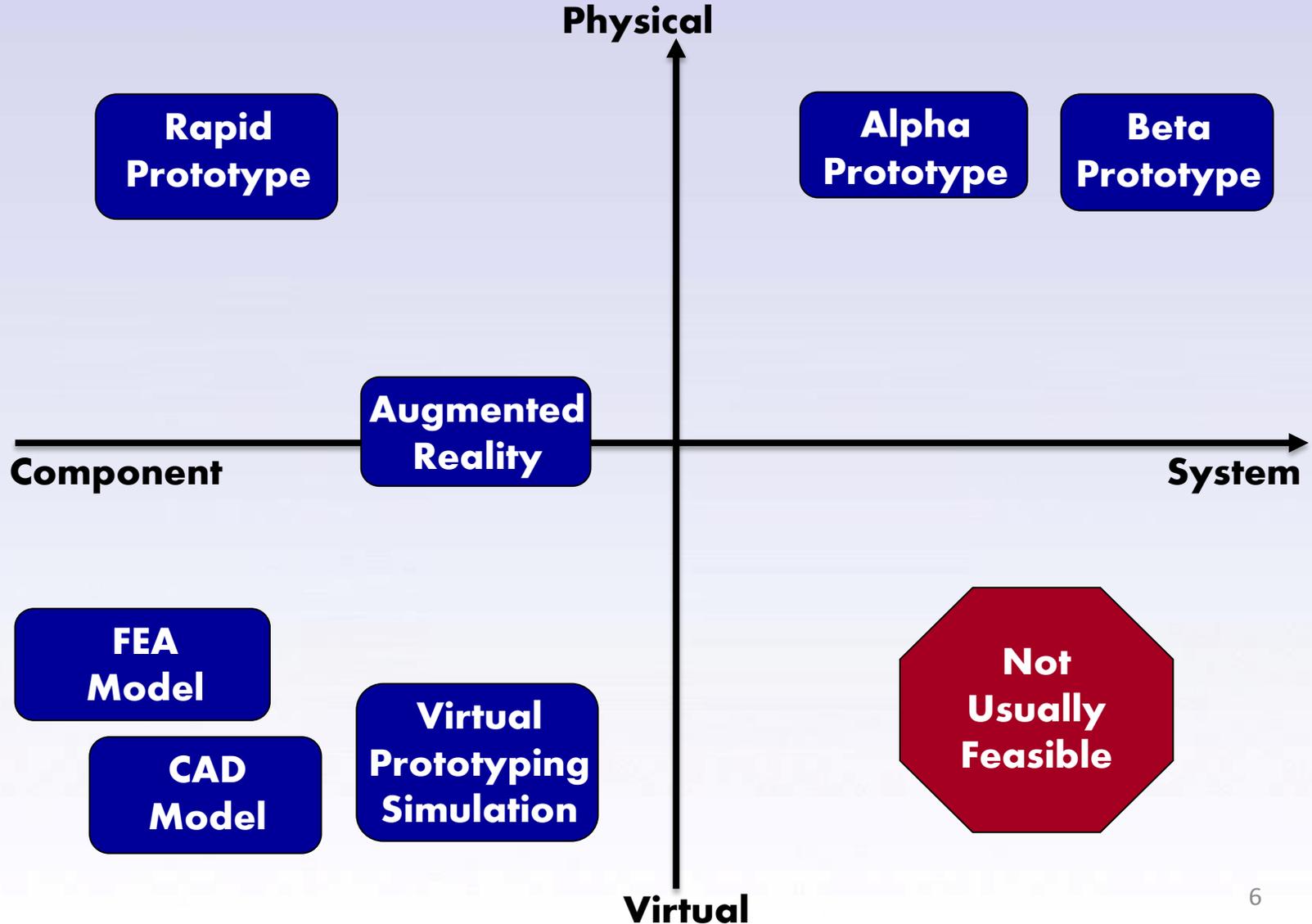
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- ❖ **Stereolithography (SLA) - 3D Systems**
- ❖ **Selective Laser Sintering (SLS) - 3D Systems, EOS**
- ❖ **Fused Deposition Modeling (FDM) - Stratasys**
- ❖ **3D Printing Technology (3DP) - Z Corp. (now 3D Systems), Ex One**
- ❖ **Inkjet - 3D Systems; Objet, Solidscan (now both Stratasys)**
- ❖ **Laser Engineered Net Shaping (LENS) – Optomec**
- ❖ **Direct Metal Deposition (DMD) – POM Group**
- ❖ **Solid Ground Curing (SGC) Cubital (out of business 2000)**
- ❖ **Ultrasonic Consolidation (UC or UAM) – Solidica (Fabrisonic)**
- ❖ **Laminated Object Manufacturing (LOM) – Helisys (Now Cubic Tech) & MCOR**

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	1D	2D
	Point Scanning	Area Filling
Pattern Material	FDM	<ul style="list-style-type: none"> • Inkjet (binder or material) • LOM • Ultrasonic Consolidation
Pattern Energy	<ul style="list-style-type: none"> • Stereolithography • Selective Sintering (laser or E-beam) • Selective Melting • LCVD (Georgia Tech) • Electrochemical Deposition 	<ul style="list-style-type: none"> • Micro-SL with DMD (or DLP) • Solid Ground Curing
Pattern Both	LENS/DMD	

❖ Prototyping – Types of prototypes



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◆ Prototyping – Design Applications

- ◆ Feel
- ◆ Assembly
- ◆ Motion/functions

◆ Visualization
◆ Communication
◆ Marketing

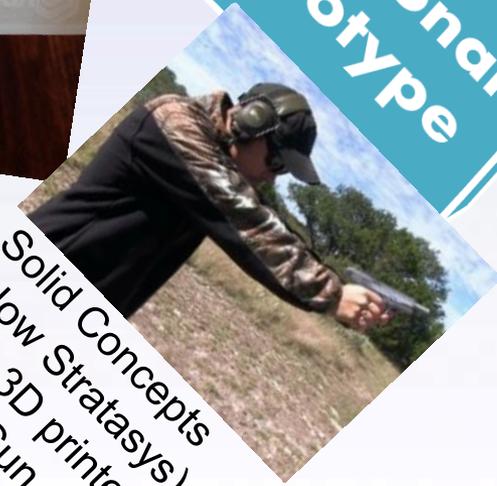
◆ **Concept Models**



◆ **Form-fit Models**



◆ **Functional Prototype**



◆ **Solid Concepts
(Now Stratasy),
First 3D printed
Metal Gun, 2013**

◆ **Subject to testing**

Applications

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Aerospace (parts & repairing)



Art, Fashion, Jewelry

Hearing aid - Siemens



Align Technology



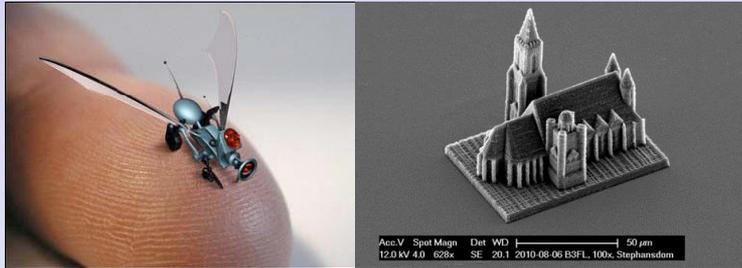
Automotive (RP & tooling)



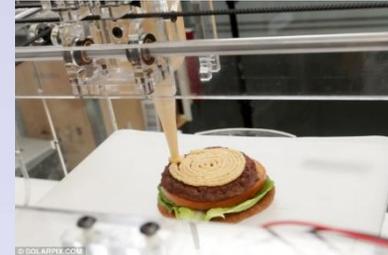
Skull implants, 2011, by Xilloc Medical

◆ Prototyping – Design Applications

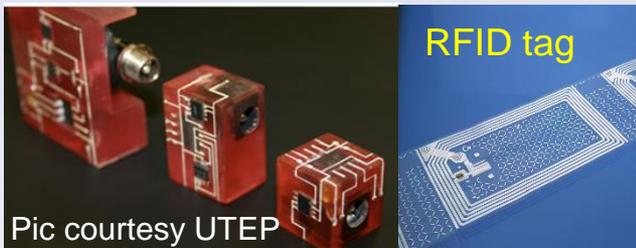
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3D nano-printing



Food



Pic courtesy UTEP

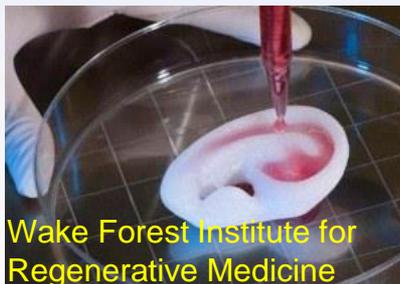
Printed electronics (structural electronics, lightweight, integrated)



12ft long 3D printed spacecraft from interstellar



Entertainment (movie, Hollywood)



Wake Forest Institute for Regenerative Medicine



Organovo, Liver printing

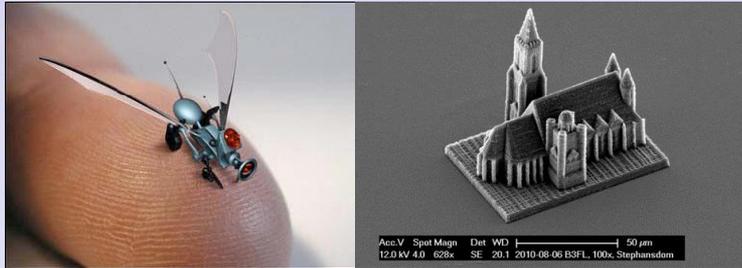
Bioprinting



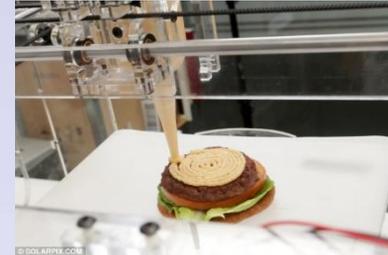
Education

◆ Prototyping – Design Applications

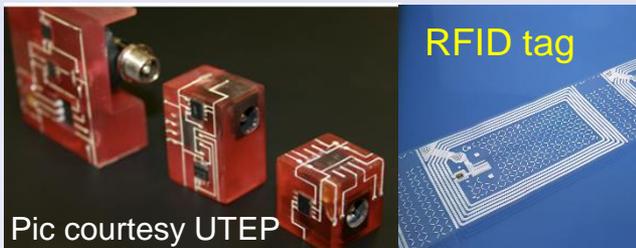
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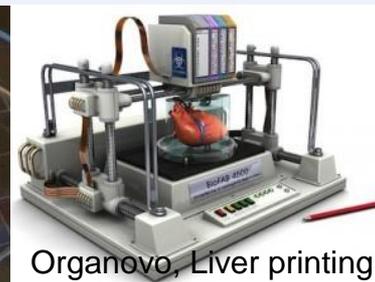
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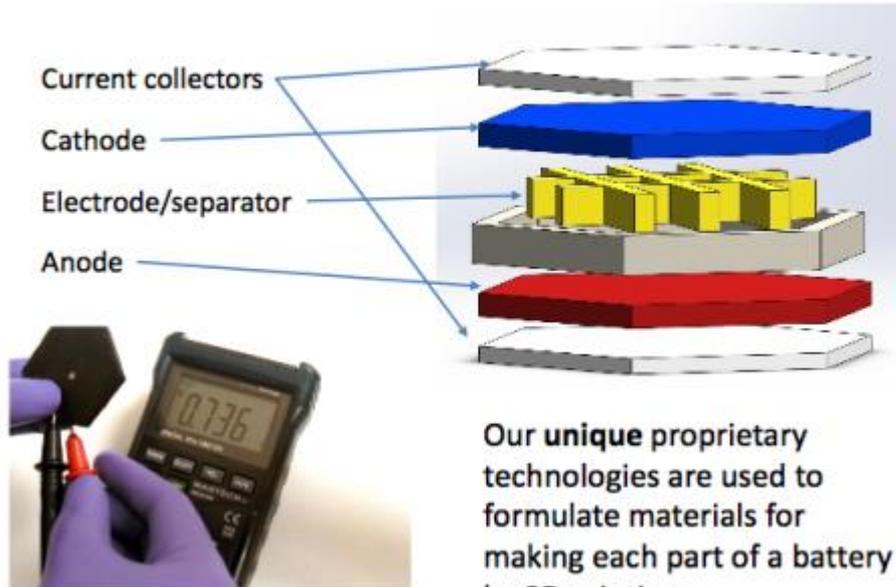
Organovo, Liver printing

Bioprinting



Education

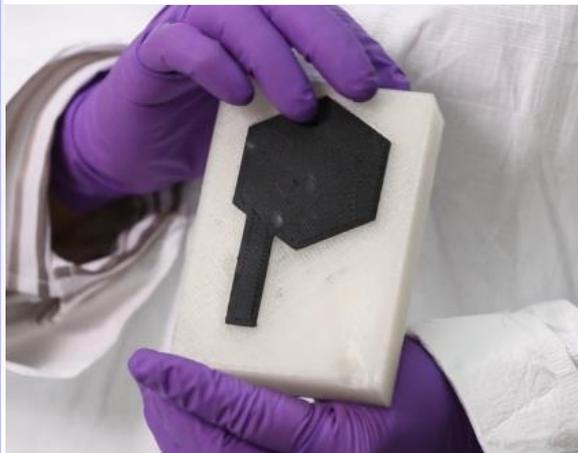
Emerging Technology: 3D Printed Battery



Working prototype

Courtesy Graphene 3D Lab

Need **MORE KILLER** Apps



Energy devices (battery, supercapacitors)



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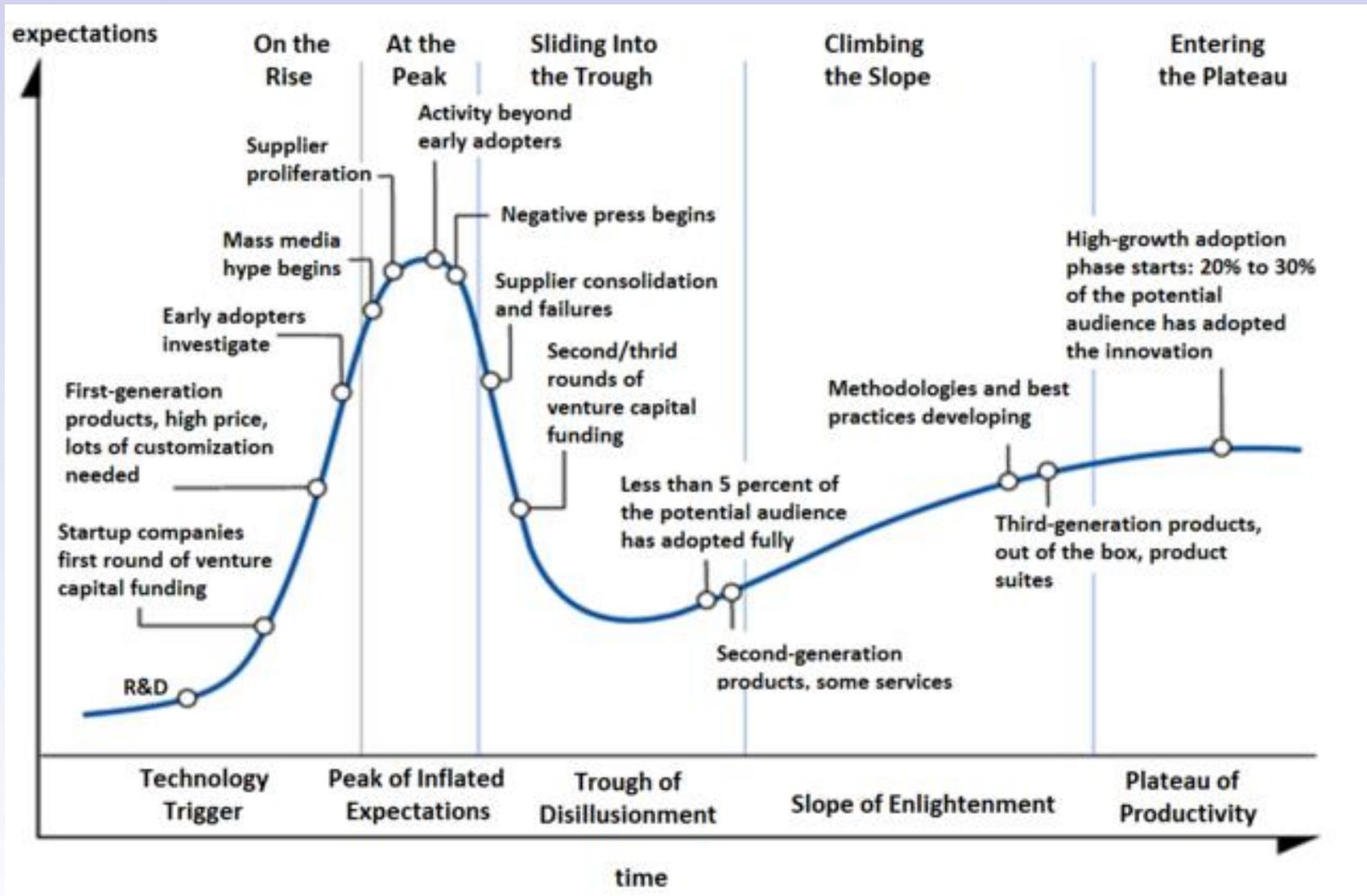


Need **MORE**
KILLER Apps

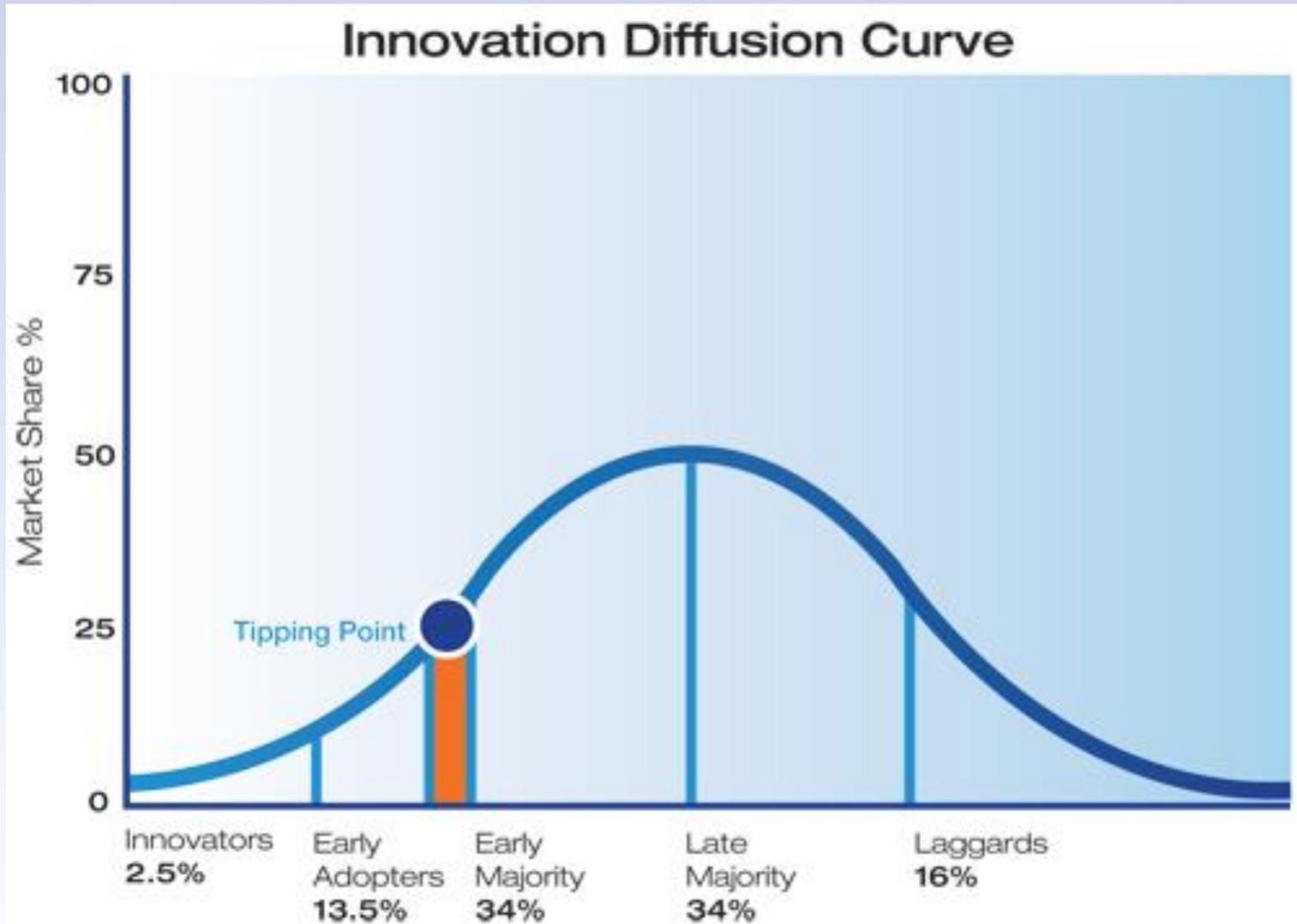
WinSun New Materials, Ma Yihe, Printing 10 homes in 24 hours

<http://blogs.wsj.com/chinarealtime/2014/04/15/how-a-chinese-company-built-10-homes-in-24-hours/>

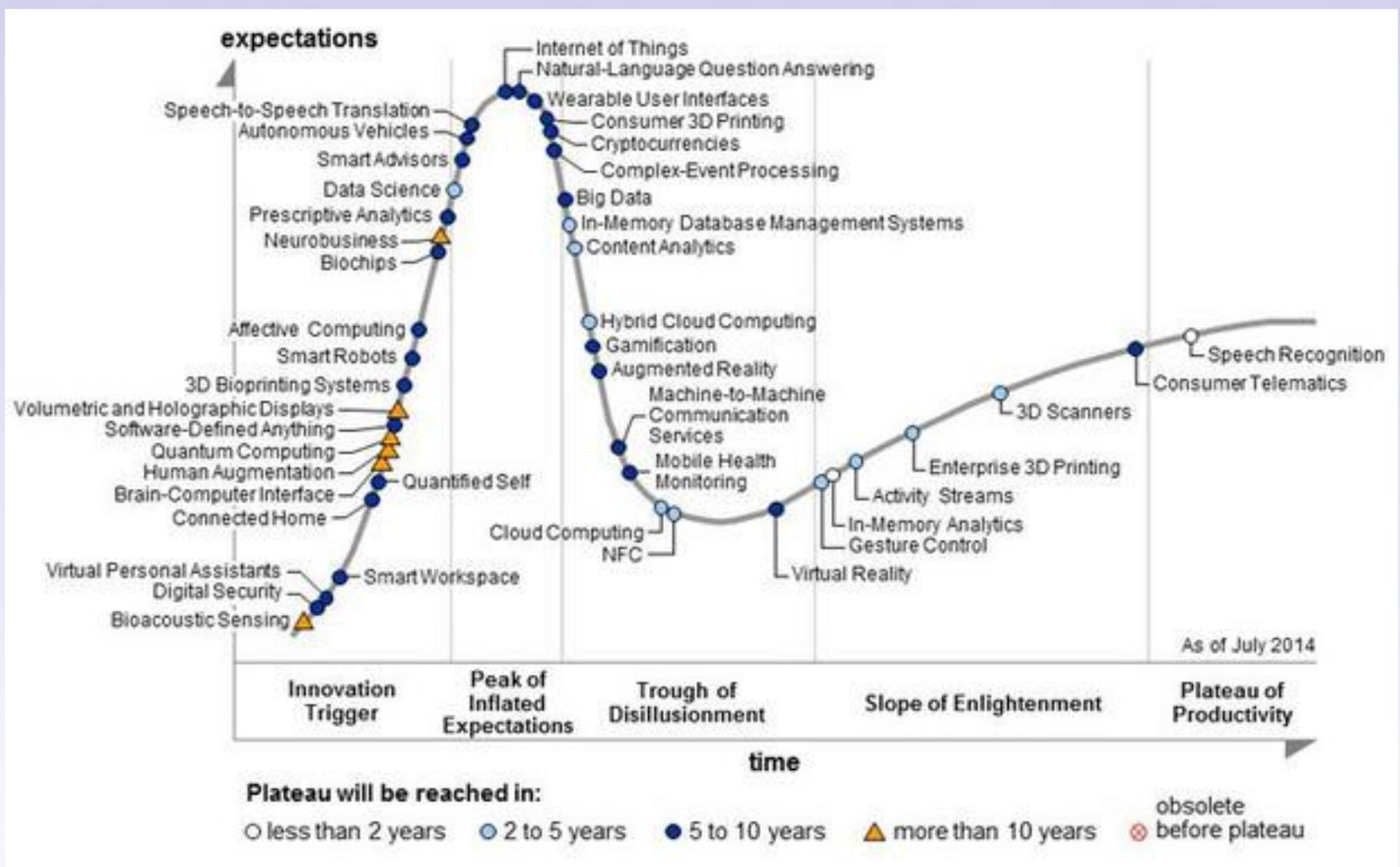
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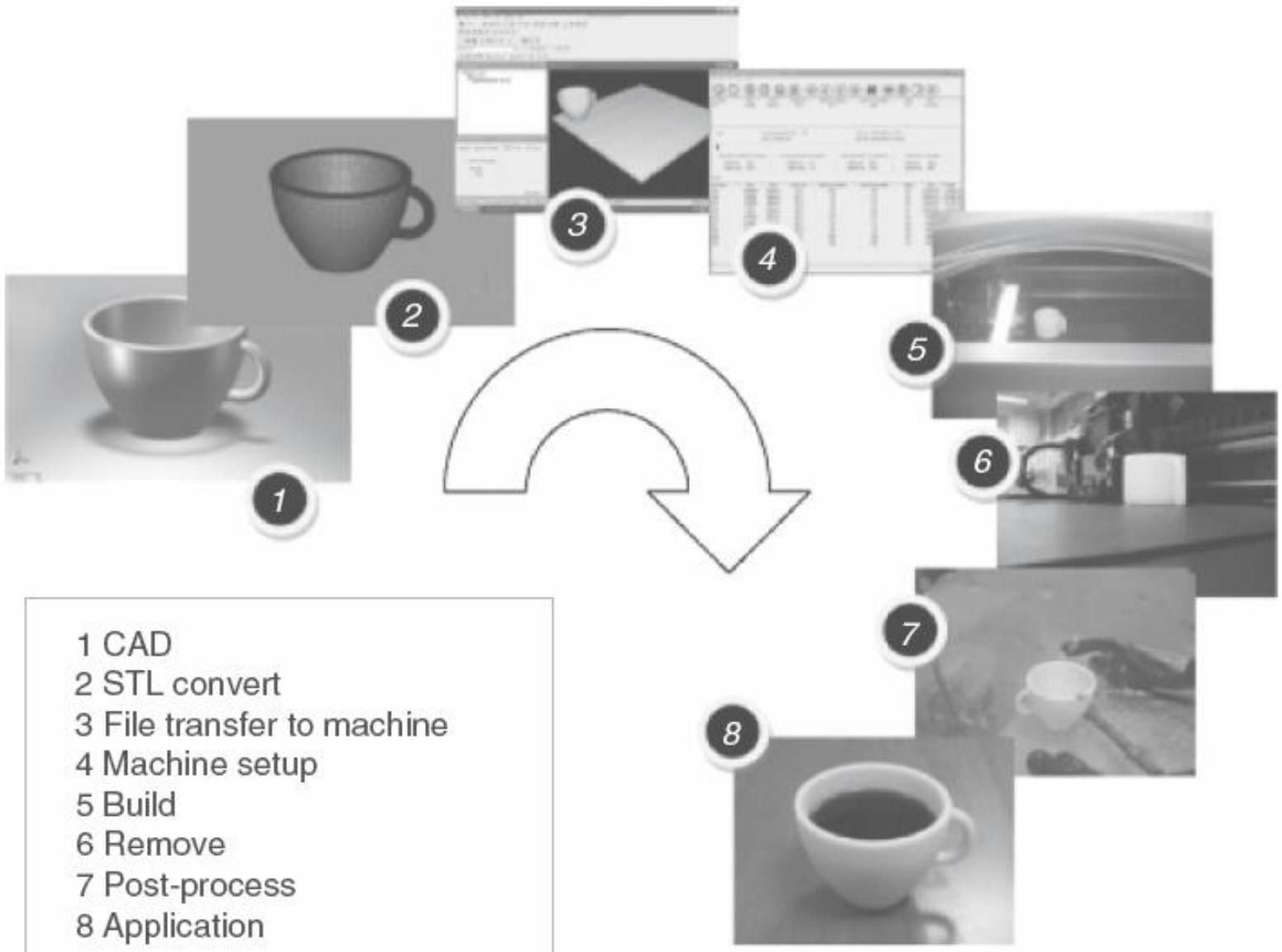
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◆ File Format – STL

solid name

facet normal ni nj nk

outer loop

vertex v1x v1y v1z

vertex v2x v2y v2z

vertex v3x v3y v3z

endloop

endfacet

facet normal ni nj nk

outer loop

vertex v1x v1y v1z

vertex v2x v2y v2z

vertex v3x v3y v3z

endloop

endfacet

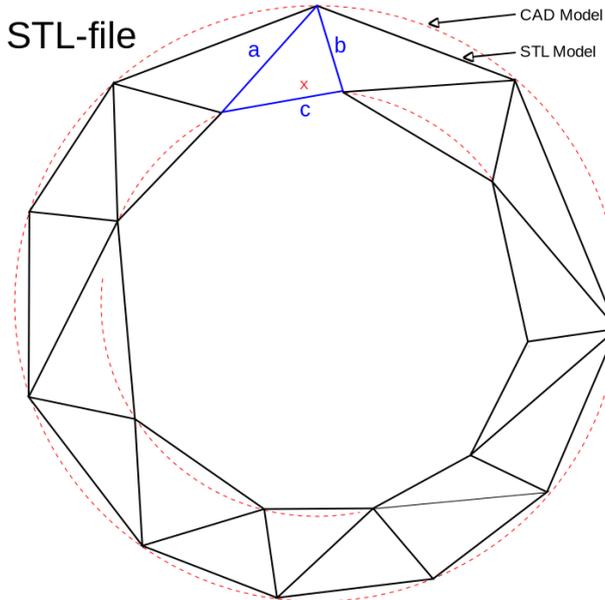
.

.

.

endsolid name

STL-file



Developed by 3D Systems: quasi-industrial standard
Name from the original technology: STereoLithography
ASCII or Binary format exist

Information Missing:

- ◆ **Color (Some systems added, e.g., VisCAM)**
- ◆ **Materials**
- ◆ **Process parameters**

Triangular "Soup"

File Format – AMF

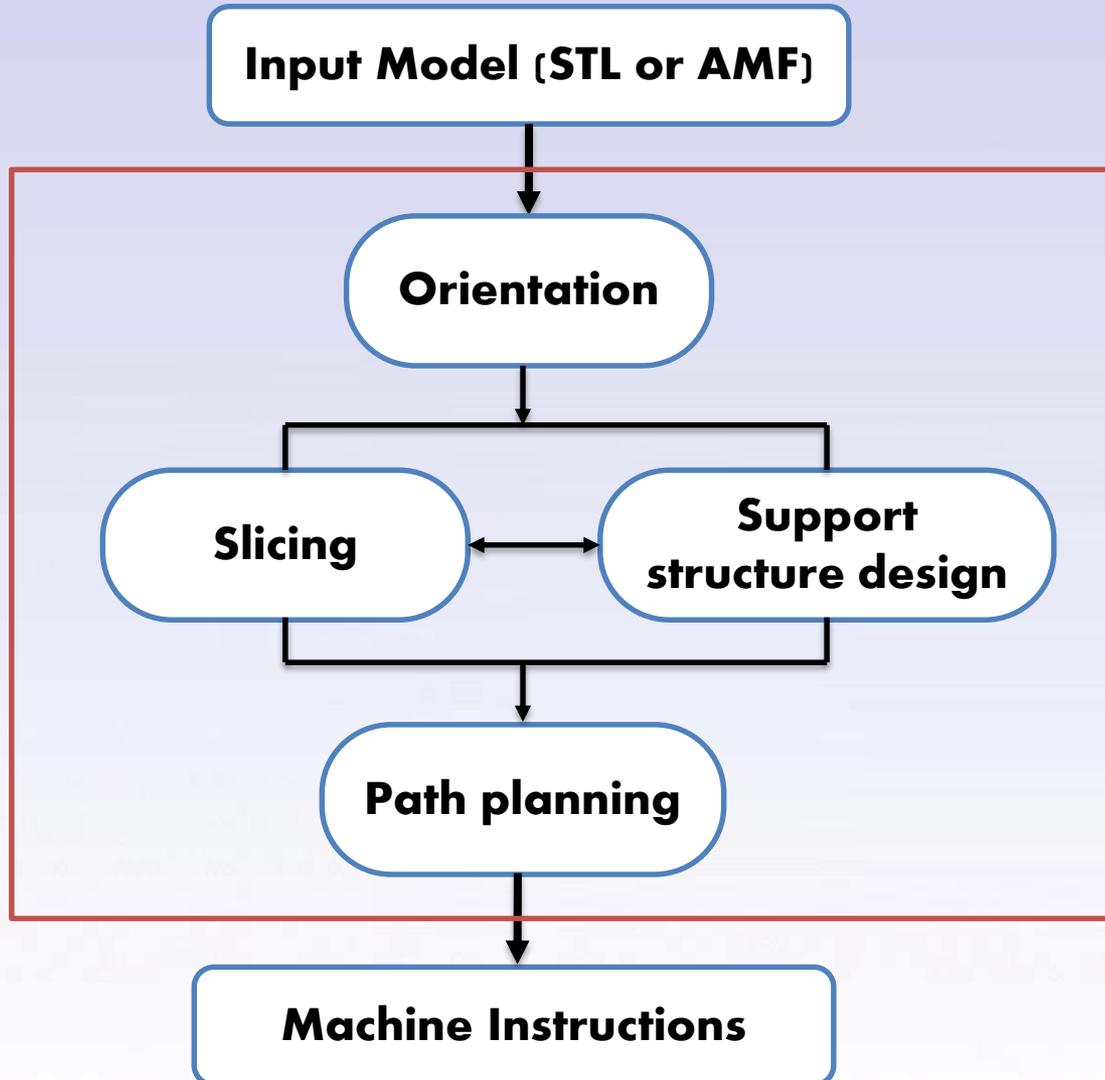
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  <metadata type="author">John Smith</metadata>
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        <vertex><coordinates><x>1</x><y>0</y><z>0</z></coordinates></vertex>
        <vertex><coordinates><x>0</x><y>1</y><z>0</z></coordinates></vertex>
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        <vertex><coordinates><x>0.5</x><y>0.5</y><z>1</z></coordinates></vertex>
      </vertices>
      <volume materialid="2">
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        <triangle><v1>2</v1><v2>1</v2><v3>0</v3></triangle>
        <triangle><v1>0</v1><v2>1</v2><v3>4</v3></triangle>
        <triangle><v1>4</v1><v2>1</v2><v3>2</v3></triangle>
        <triangle><v1>0</v1><v2>4</v2><v3>2</v3></triangle>
      </volume>
      <volume materialid="3">
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        <triangle><v1>4</v1><v2>3</v2><v3>2</v3></triangle>
        <triangle><v1>4</v1><v2>2</v2><v3>1</v3></triangle>
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  </material>
  <material id="3">
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    <color><r>0</r><g>0.9</g><b>0.9</b><a>0.5</a></color>
  </material>
</amf>

```

- ◆ Additive Manufacturing File
- ◆ ISO/ASTM Standard, 2011
- ◆ Machine independent (no layer or process information)
- ◆ XML-based format
 - ◆ <object>: volume of materials
 - ◆ <material>
 - ◆ <texture>
 - ◆ <metadata>
 - ◆ ...

❖ Software pipeline – From model to machine instructions



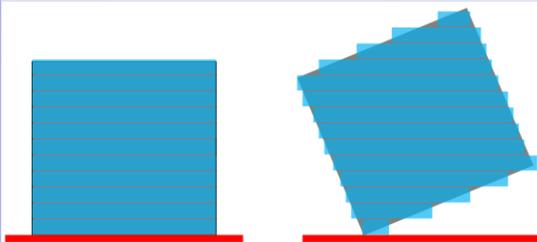
- ❖ **Orientation**
- ❖ **Support structure**
- ❖ **Slicing**
- ❖ **Path planning**
- ❖ **Machine instructions**

Orientation Determination

Factors

- ❖ Surface accuracy
- ❖ Build time
- ❖ Support volume
- ❖ Support contact area
- ❖ Mechanical properties

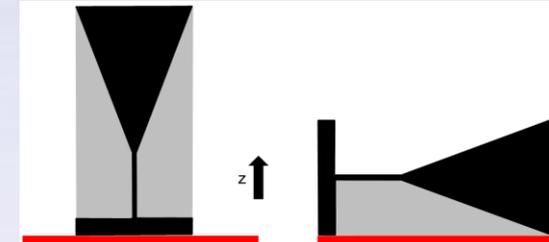
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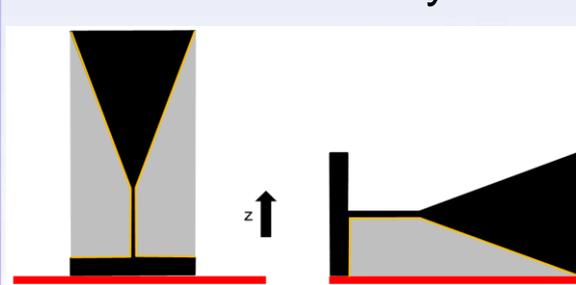
Surface accuracy



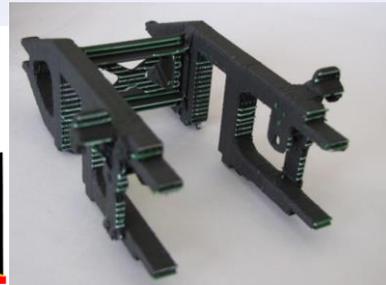
Build time



Support material volume



Support contact area



After support removal



Mechanical property (weaker in Z direction)

- ❖ Manual: user
- ❖ Semi-auto: user and software
- ❖ Auto: software

Support structure design

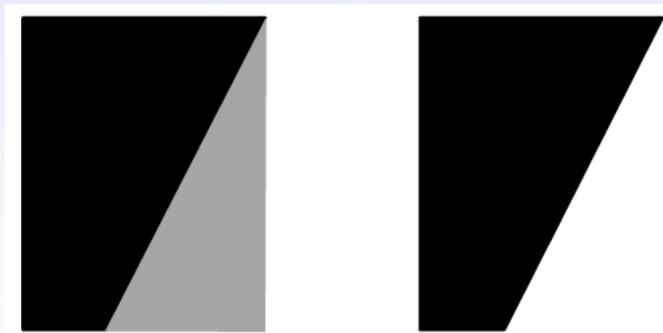
- ❖ "Powder" bed based processes: **Do NOT** need support structures: SLS, SLM, etc.
- ❖ Others **DO**: SLA, FDM, Inkjet deposition, etc.

- ❖ Orientation
- ❖ **Support structure**
- ❖ Slicing
- ❖ Path planning
- ❖ Machine instructions

Objectives

- ❖ Prevent curling due to internal stress
- ❖ Supporting overhangs
- ❖ Maintaining stability

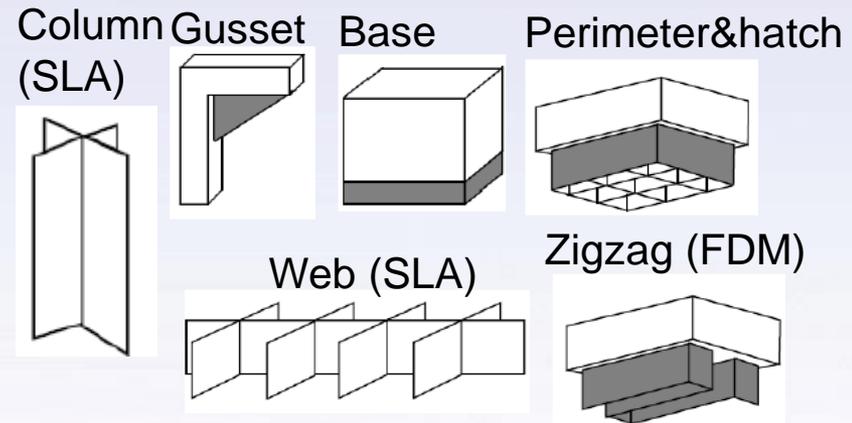
Empirical "rules"



Inkjet

FDM (up to 45 degrees)

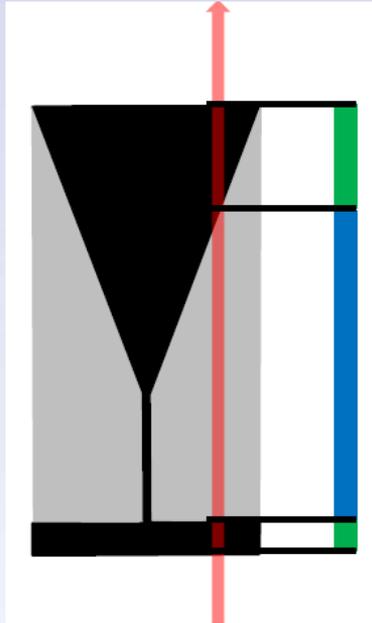
Support types



Support structure design

Algorithms for generating support structures

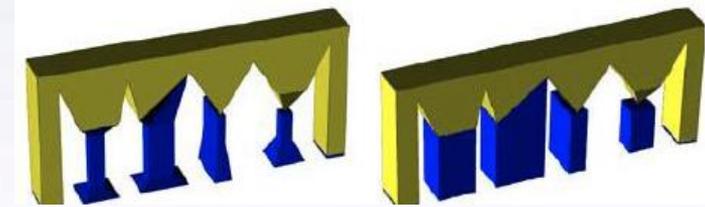
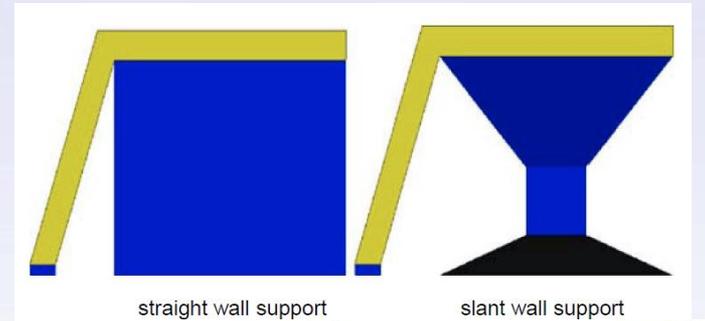
Simple ray casting algorithm



- ❖ Orientation
- ❖ **Support structure**
- ❖ Slicing
- ❖ Path planning
- ❖ Machine instructions

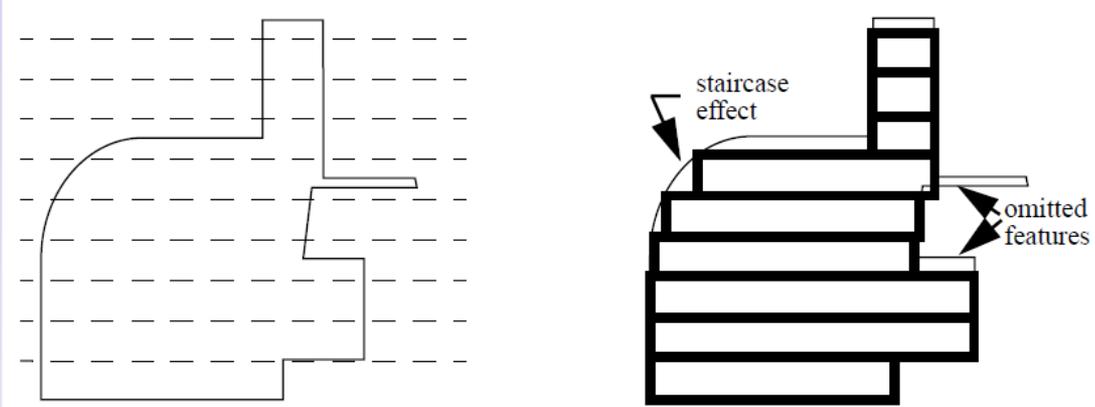
Advanced algorithms

- ❖ Minimize the use of support material
- ❖ Or for other purposes, such as minimize curling



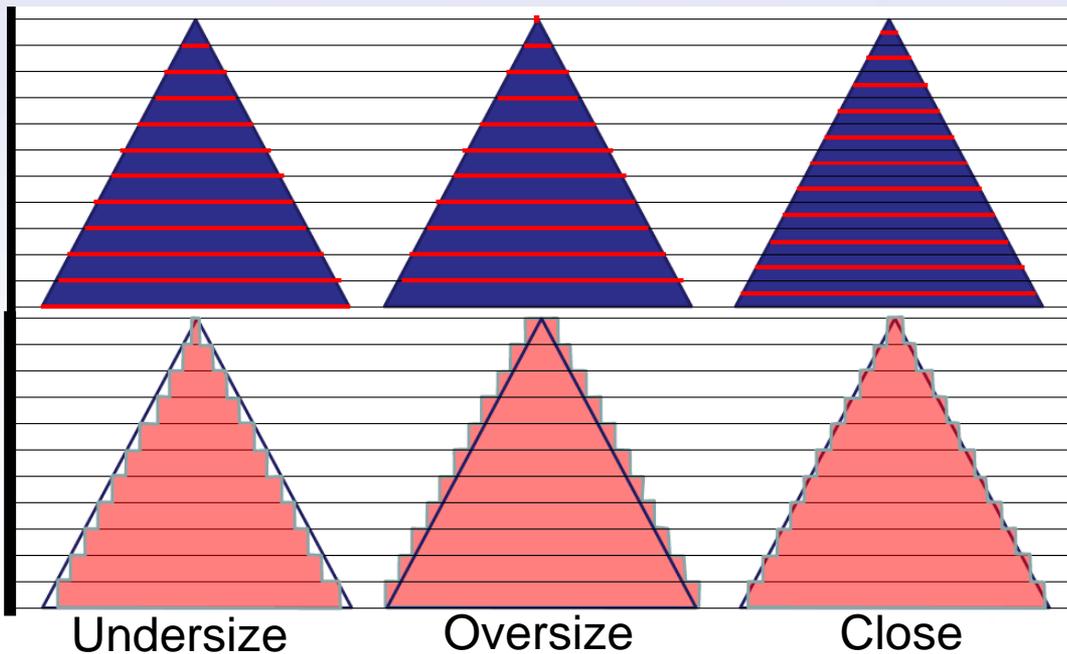
Optimized VS unoptimized

❖ Slicing



- ❖ Orientation
- ❖ Support structure
- ❖ **Slicing**
- ❖ Path planning
- ❖ Machine instructions

For each z, compute intersection of a plane with the model



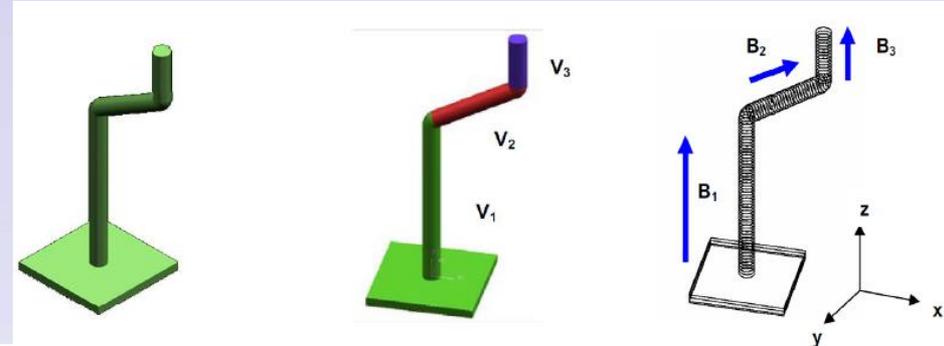
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❖ Slicing

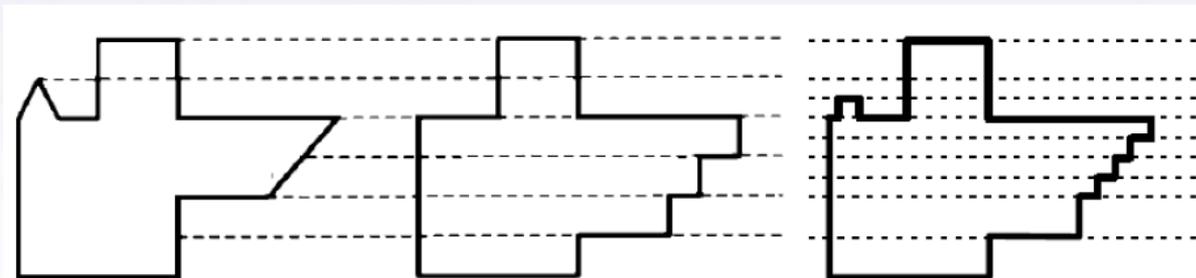
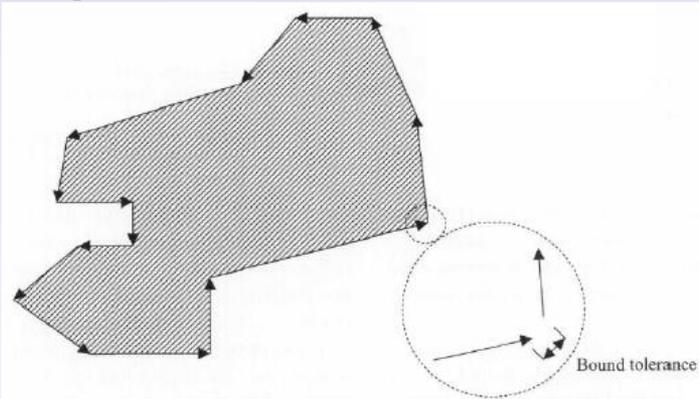
Slicing STL

- ❖ **Voxelization (determine inside or outside)**
- ❖ **Then extract contours**
- ❖ **Epsilon issues (machine precision)**

Many research on slicing



Multi-direction slicing



input model

uniform slicing

adaptive slicing

Adaptive slicing

◆ Path planning

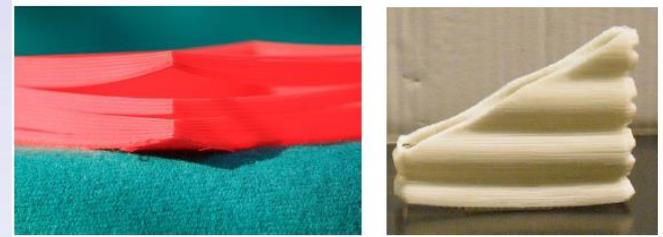
Two types

- ◆ 2D (area filling at once): raster-based
- ◆ 1D scanning tool path: vector-based

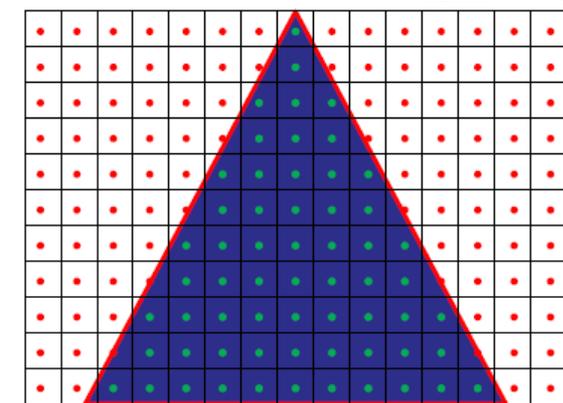
Factors

- ◆ Surface accuracy
- ◆ Build time
- ◆ Mechanical properties:
stiffness, strength, distortion

- ◆ Orientation
- ◆ Support structure
- ◆ Slicing
- ◆ Path planning
- ◆ Machine instructions

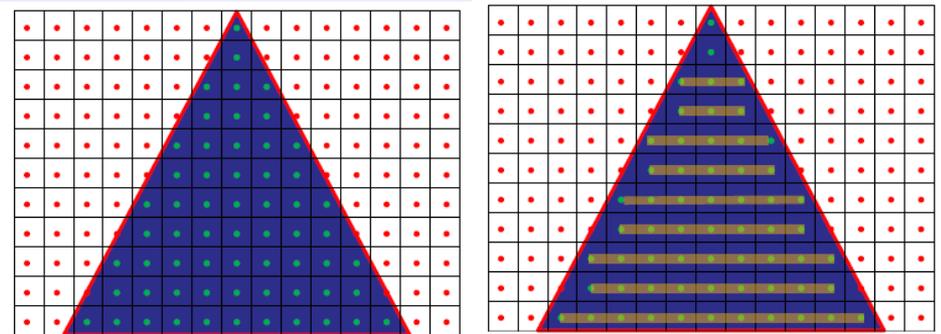


For raster-based: e.g., inkjet



After voxelization,
superimpose a voxel grid

For vector-based: e.g., SLA

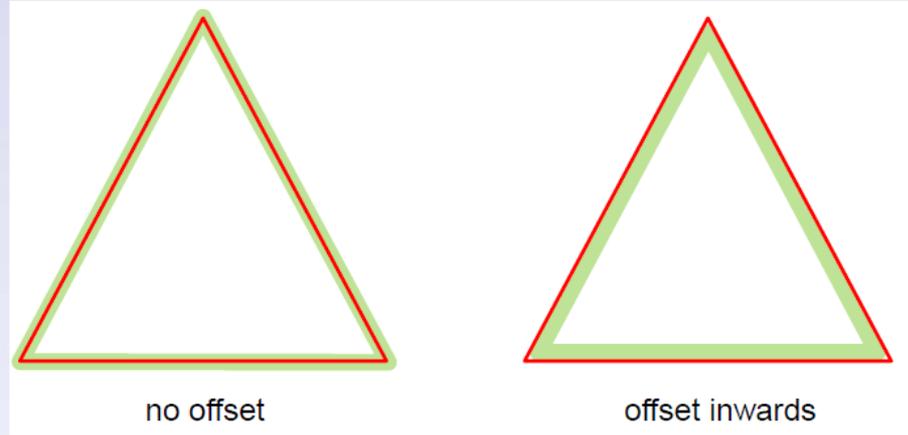


1. Superimpose a voxel grid
2. Rows and columns used as tool paths

❖ Path planning

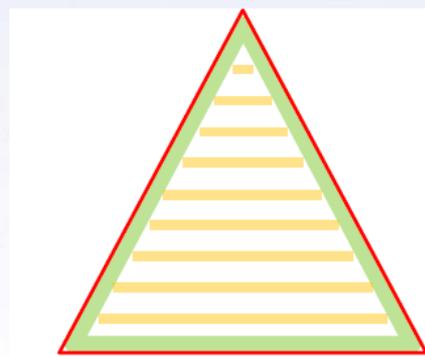
For vector-based

❖ Tracing contours: improved surface accuracy

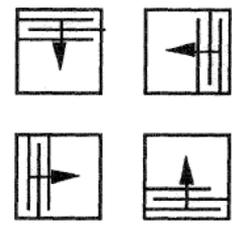


- ❖ Orientation
- ❖ Support structure
- ❖ Slicing
- ❖ **Path planning**
- ❖ Machine instructions

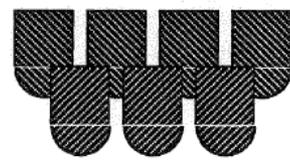
❖ Tracing contours + filling interiors



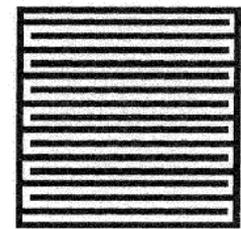
contour offset inwards + interior fill



alternate sequencing



staggered weave



retracted hatch

Advanced fill patterns: STARWEAVE

❖ Machine Instructions

❖ **Raster-based, e.g., inkjet:**
proprietary, can be exported as image files (PNG, BMP, etc.)

❖ **Vector-based, e.g., FDM:**
1. **G-code (dominant);**
2. **SLI by 3D Systems**

G-Code

❖ **Developed at MIT in 1950s for CNC milling**

❖ **Simple instructions telling machine**

- ❖ **where to move**
- ❖ **how fast to move**
- ❖ **what path to move**

Sample instructions:

-**G00: Rapid move**

•does not necessarily move in a single straight line between start point and end point. It moves each axis at its max speed until its vector is achieved.

-**G01: Linear interpolation**

•specify the start and end points, and the control automatically calculates the intermediate points to pass through that will yield a straight line

-**G02: Circular interpolation, clockwise**

- ❖ **Orientation**
- ❖ **Support structure**
- ❖ **Slicing**
- ❖ **Path planning**
- ❖ **Machine instructions**

❖ Post-processing – depends on process

Steps:

- ❖ Remove the part from the build platform and depowder (if powder based) and cleaning;
- ❖ Remove the support structures from the part using appropriate tools
- ❖ Post-curing (SLA)
- ❖ Surface finishing

❖ Example of SLA



Remove build platform and the part



Rinse in IPA



Remove supports

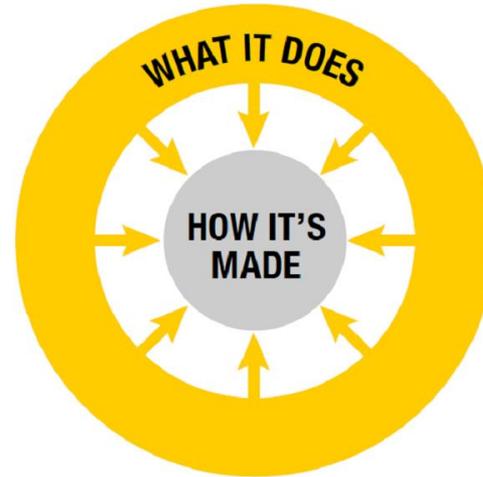


Finish w. sand paper and mineral oil

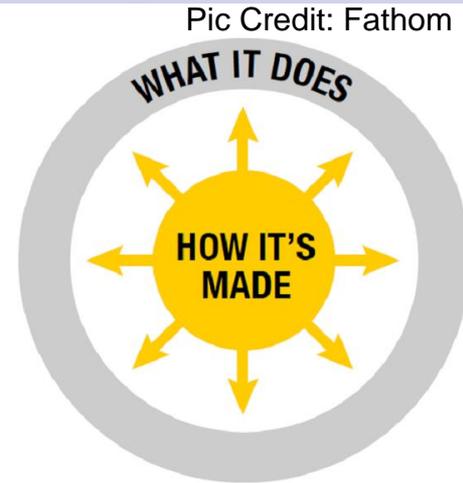
Design Freedom

Complexity is nearly free

- Geometry
- Material
- System

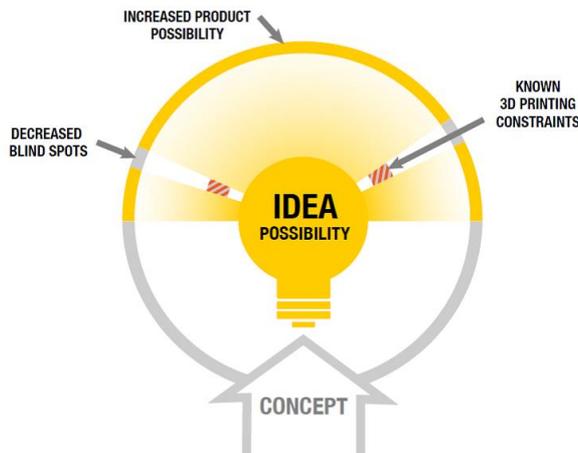


ADDITIVE MFG
Drives Innovation

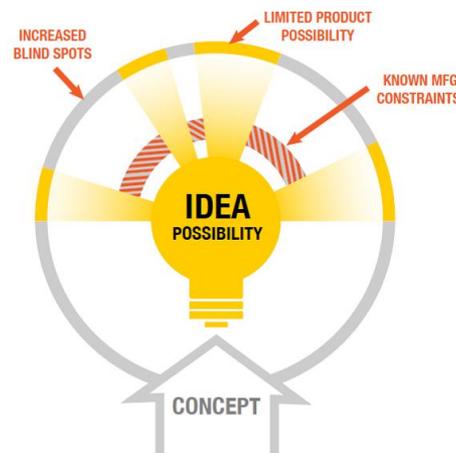


TRADITIONAL MFG
Limits Design

DESIGN FREEDOM: Increase Product Possibility



ADDITIVE MFG
Increase Design Possibility
with Minimal Blind Spots and Constraints

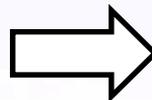


TRADITIONAL MFG
Limits Design Possibilities
with Many Blind Spots and Constraints

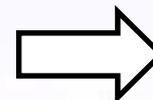
◆ Digital



Mass Production



Customization



Mass Customization

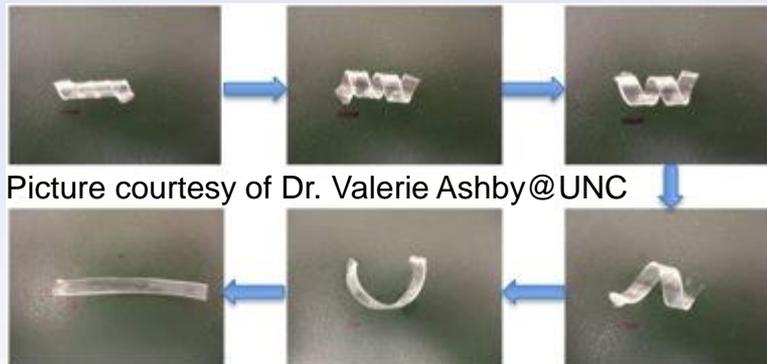


❖ Integrated smart structures

- ❖ **Reduced volume and weight (make everything more "compact" and "wearable")**
- ❖ **Smart: structures that can sense, communicate, respond, and process information; (no more "dead" structures)**

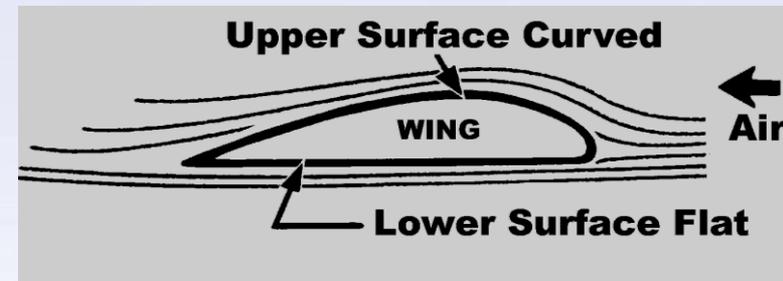


Mimosa



Picture courtesy of Dr. Valerie Ashby@UNC

Shape memory polymers – change structure at external stimulus



Design a wing structure that can adapt its shape to the environment



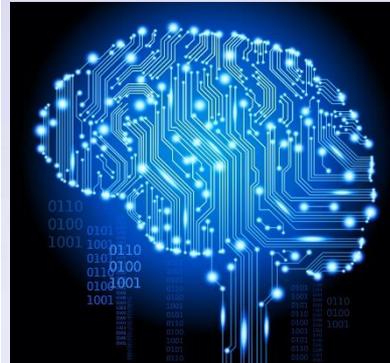
Imagine: a shoe that can change size, color, and shape

- ❖ **Blur the boundary between physical and digital world**
- ❖ **Giving the autonomous producing capability to machines**
- ❖ **Life: sense, information processing, responding (executing instructions), metabolism + **autonomous reproduction****

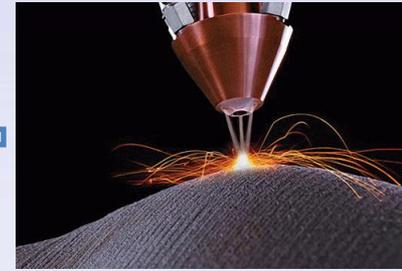
What is AM
Applications
How does it work
Advantages
Opportunities
Challenges
AM Industry



Robotics



Artificial Intelligence Internet of things

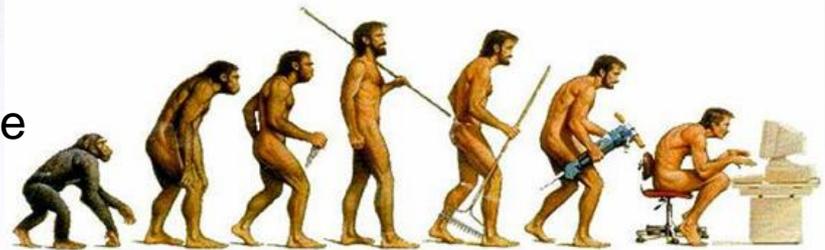


3D printing

A self-evolving world that doesn't need humans

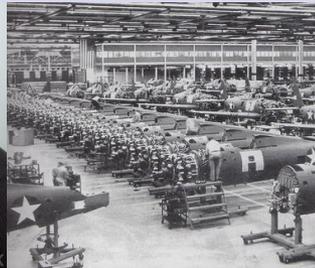


Self-Repair
Self-Replicate
Self-Evolve



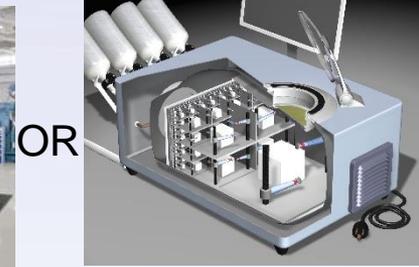
◆ Revolutionizing product value chain

What we do now



Professional Design Mass Production Transportation Local distribution Shopping Mall

What we will do when we get there



Custom Design
with Professional
Design Software

Internet

Local Production Center
with 3D Printers

OR

Desktop Factory

Need to digitalize most of our current products (we are currently only able to 3D print a negligible tiny portion of our current products)

- What is AM
- Applications
- How does it work
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❖ **TOO Slow** ($< \sim 1000 \text{ cm}^3/\text{hr}$)



Build a house brick by brick



Parallel building – scaling up

- ❖ **Material unit volume** (resolution^3) – **use coarse resolution**
- ❖ **Deposition frequency** ($\sim 10\text{kHz}$) or **scanning speed** ($< \sim 1000 \text{ mm/s}$) – **increase frequency to MHz + parallel building**
- ❖ **Delay between layers** ($< \sim 1\text{s}$) – **continuous building**
- ❖ **Post-processing** ($\sim 1\text{x}$ of build time) – **eliminate it**

❖ Materials

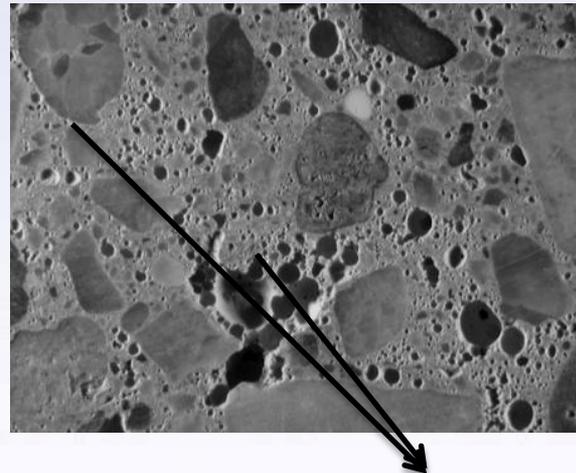
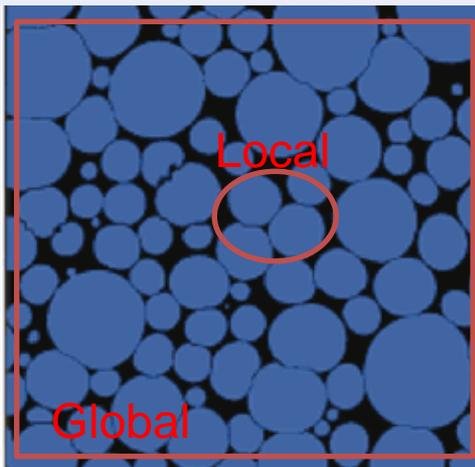
❖ Energy patterning

- ❖ **Common choices: photopolymer, thermoplastics, Titanium (alloys), steel;**
- ❖ **Difficult materials: aluminum, ceramics, biomaterials, etc.**

❖ Material patterning (sensitive to material properties)

- ❖ **Viscosity (e.g., inkjet, < ~40cP)**
- ❖ **Surface tension (e.g., syringe)**

❖ Properties



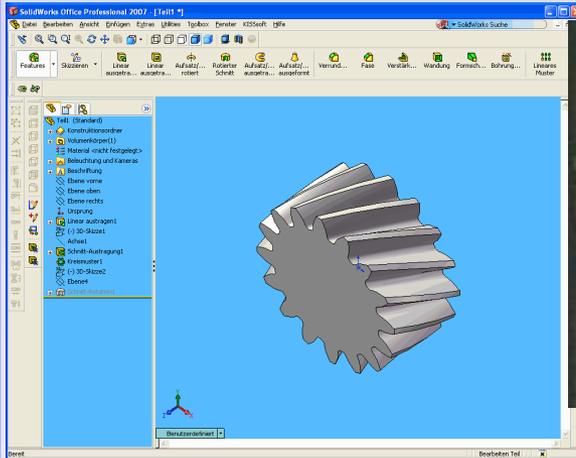
Core idea of AM:
material joining
(reduce material
interfaces) →
undesired material
interfaces lead to
inferior material
properties

Voids/Material interfaces:
Lead to stress concentration, etc.

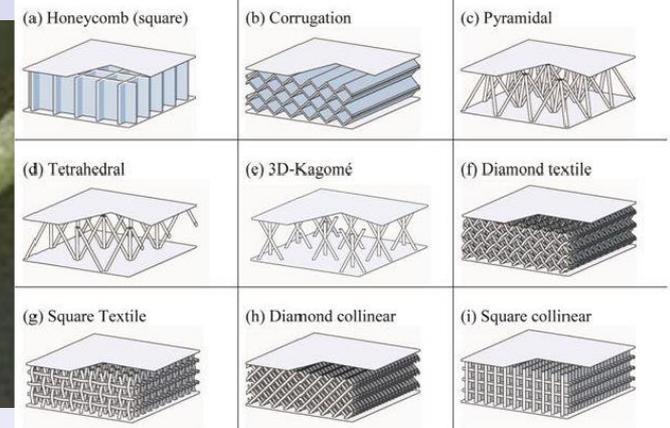
Challenges

- ◆ **Design complexity (Mutliscale & multi-resolution) from design freedom**
 - ◆ **Geometry**
 - ◆ **Material composition**
 - ◆ **Local process parameters (open loop, repeatability)**

<http://www.virginia.edu/ms/research/wadley/cellular-materials.html>

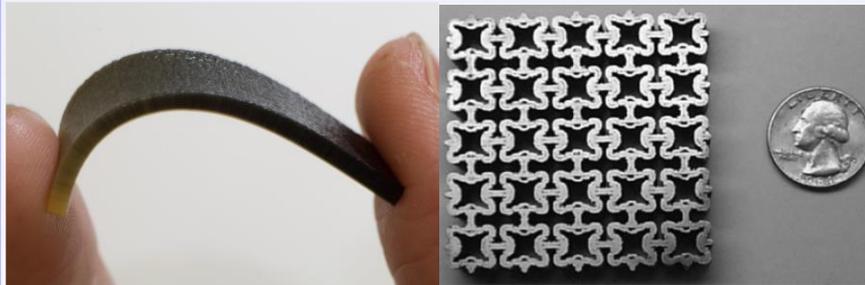


Courtesy of Dr. David Rosen

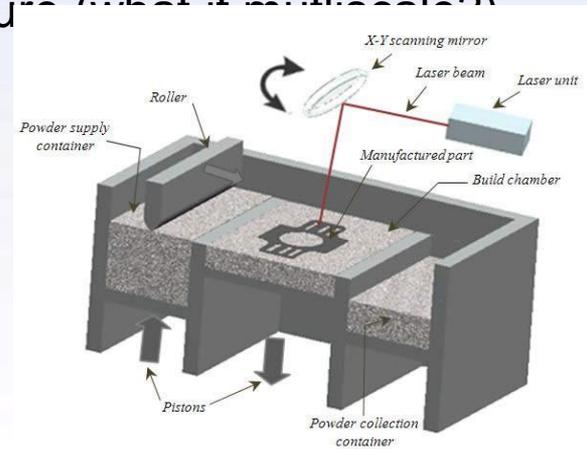


Current CAD system

Design and optimize lattice structure and cellular structure (what if multiscale?)



Design of material composition (functional graded material, metamaterial)



Local process parameters

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❖ Killer applications

❖ Faster, cheaper, better solution for large-scale common & important problems



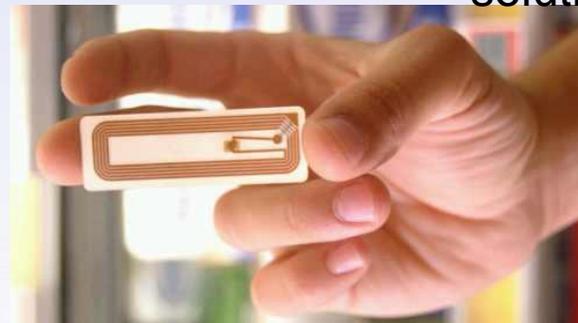
Aerospace (multi-billion dollar industry)



Align Technology (multi-billion dollar industry)



Need **MORE** SIMPLE IDEAS for better solutions



Printed RFID (multi-billion dollar industry)



Printed flexible display

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AM Industry

3D Content Provider



CAD



3D Scanners



http://reprap.org/wiki/Printable_part_sources

Online Repositories

Marketplace (Share, buy, and sell designs)

shapeways*

i.materialise

sculpteo

Sell prints

3D Burrito

LAYER BY LAYER

Sell design files

cgtrader



Cubify™

Sell both

yeggi

Google custom search

Search engine

<http://makin society.com/2013/07/37-3d-printing-marketplaces-to-share-buy-and-sell-3d-designs/>

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3D Printing service



Provide local store printing service



Connect to local 3D printers (cloud)



<http://www.wohlersassociates.com/service-providers.html>

Solution providers (industrial)

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Machine suppliers

	Major Players	Materials
SLA	  	Photopolymers
FDM	   	Thermoplastics
Inkjet	     	Photopolymer; Metal/ceramics in suspension
Powder (bed)	          	Powders: Metal, ceramics, plastic, glass, plaster, sand, etc.

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Software (convert STL files to machine instructions)



http://reprap.org/wiki/Useful_Software_Packages



Closed source



Open source

Material suppliers



Filaments

Photopolymers



Printable inks

Customers



Aerospace & Defense



Architecture & Geo



Automotive



Education



Energy



Healthcare



Jewelry



Hobbyist



Consumer

<http://www.3dsystems.com/solutions/overview>

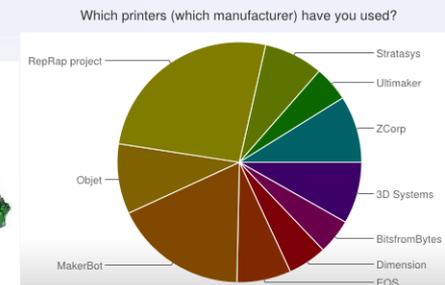
Open source community <http://reprap.org/>



Evan Malone and Hod Lipson
Cornell, 2006, syringe based
(dying after 2012)



Adrian Bowyer, U of Bath, UK; Self-replicating,
FFF based, Arduino-based control, Thriving





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